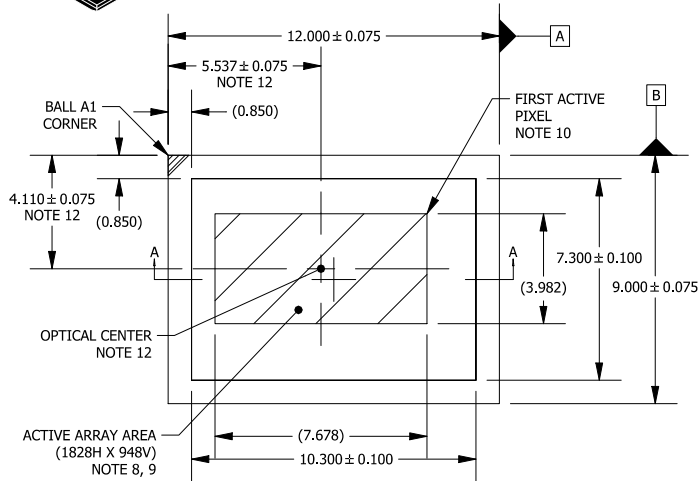
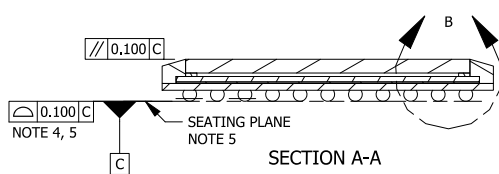


IBGA87 12x9
CASE 503BF
ISSUE C

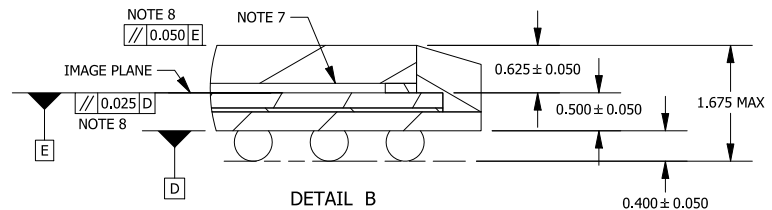
DATE 06 AUG 2019



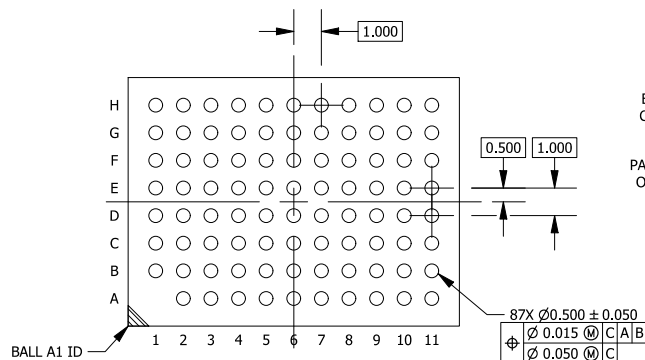
TOP VIEW



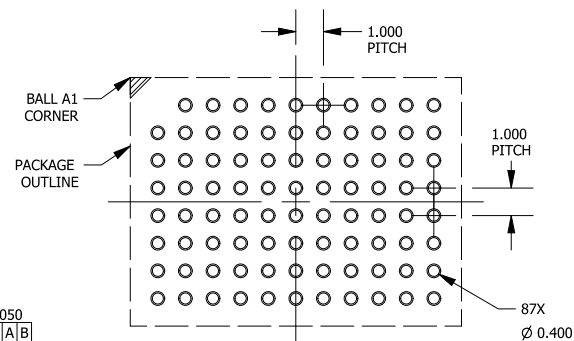
SECTION A-A



DETAIL B

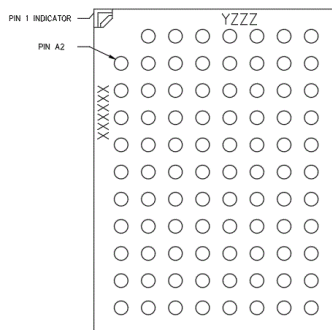


BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



GENERIC MARKING DIAGRAM*

XXXX = Specific Device Code
Y = Year
ZZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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